# Revisions

Rev. 0.0 : Development version

Rev. A.0 : Initial Release
- Change L1 to DR74-2R2-R
- Change U3 to W25Q16DWSSIG (SOIC8 208mil)

Rev. B.0 : minor BOM change
- Do not install TPGND3

ESD 2514167
PCB 2514168
CCA 2514169

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|---|---|---|---|
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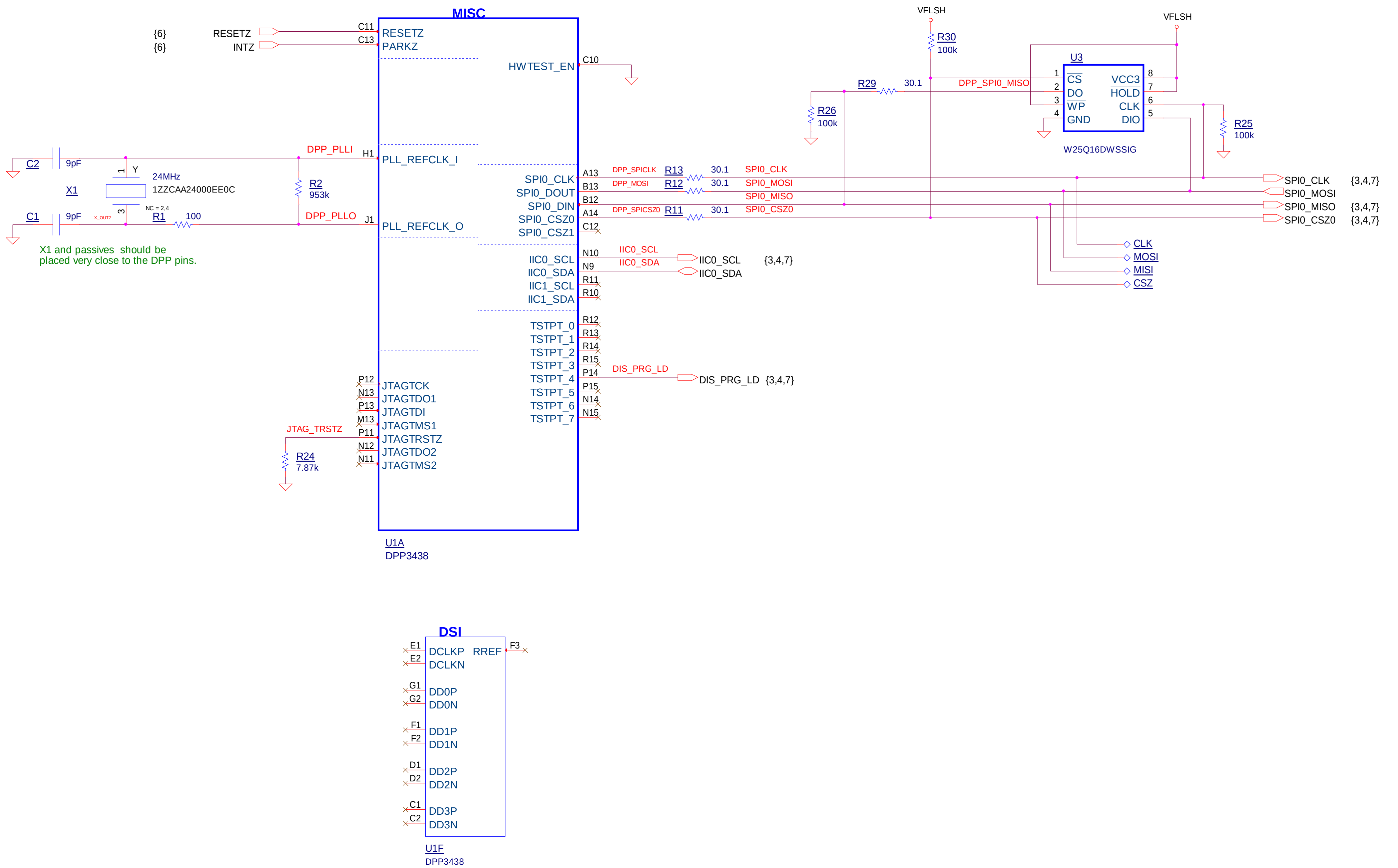
| SYS | Dan Morgan | --- | TITLE TIDA-00384 DLP LightCrafter Display 3010 EVM |
| APVD | Jeff Dennis | --- | DRAWING NO 2514167 REV B.0 |
| QA | --- | --- | 11 x 17 Orcad Capture 16.2 SHEET 1 of 7 |

# DPP3438 Clock, Reset, SPI and Flash Memory



X1 and passives should be
placed very close to the DPP pins.

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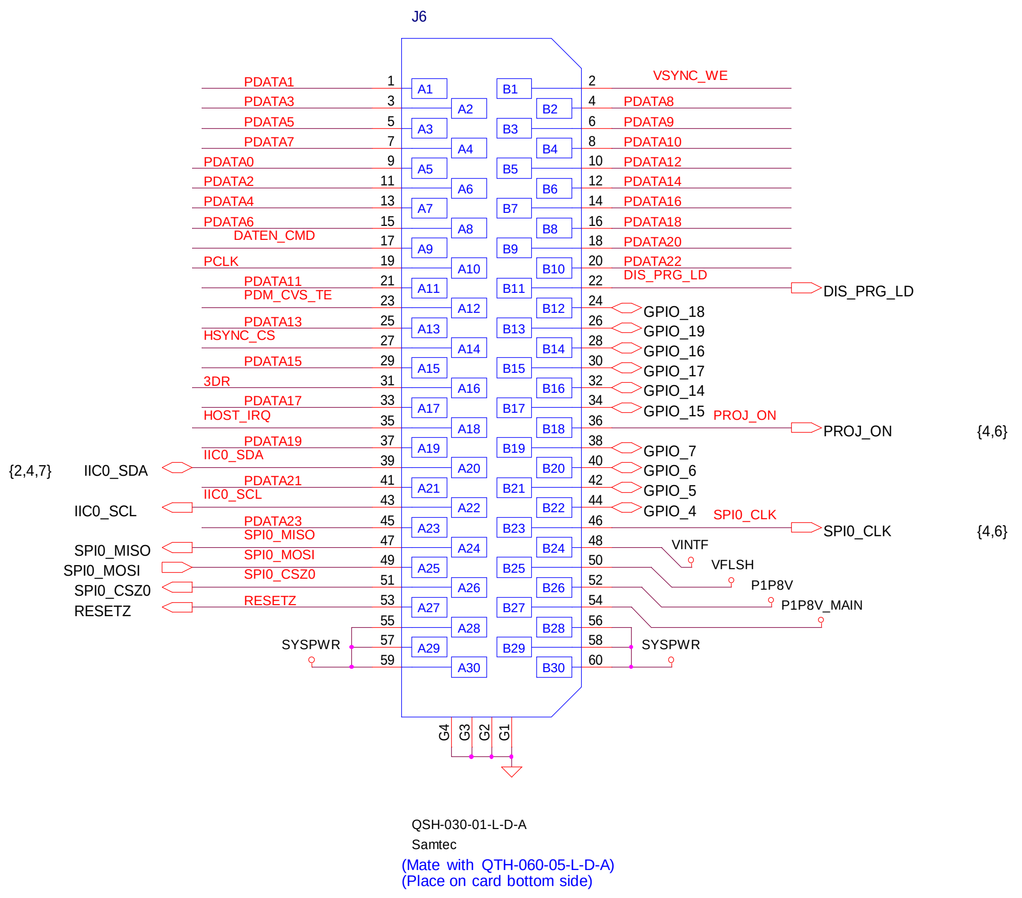
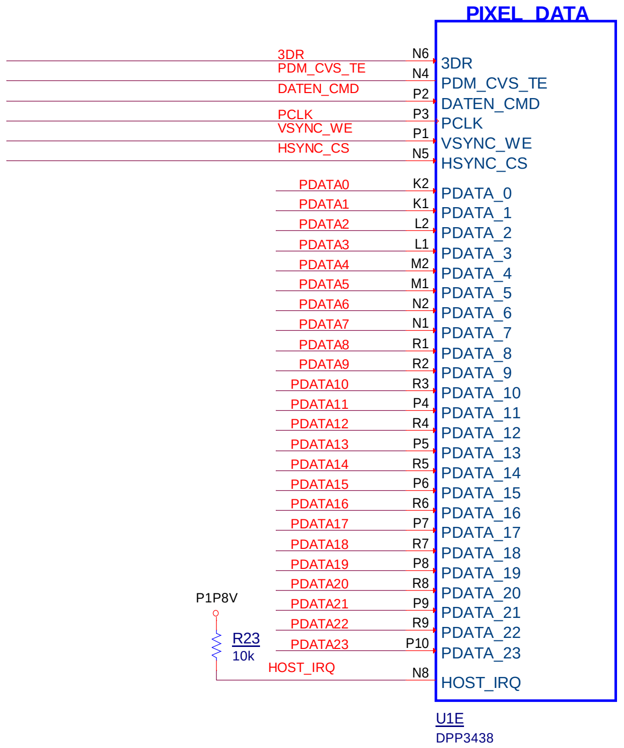
| ENGR Kevin Lowderman | JUN-05-2014 | TITLE DPP3438 MISC | |
| SYS Dan Morgan | --- | DRAWING NO 2514167 | REV B.0 |
| APVD Jeff Dennis | --- | 11 x 17 Orcad Capture 16.2 | SHEET 2 of 7 |
| QA --- | --- | | |





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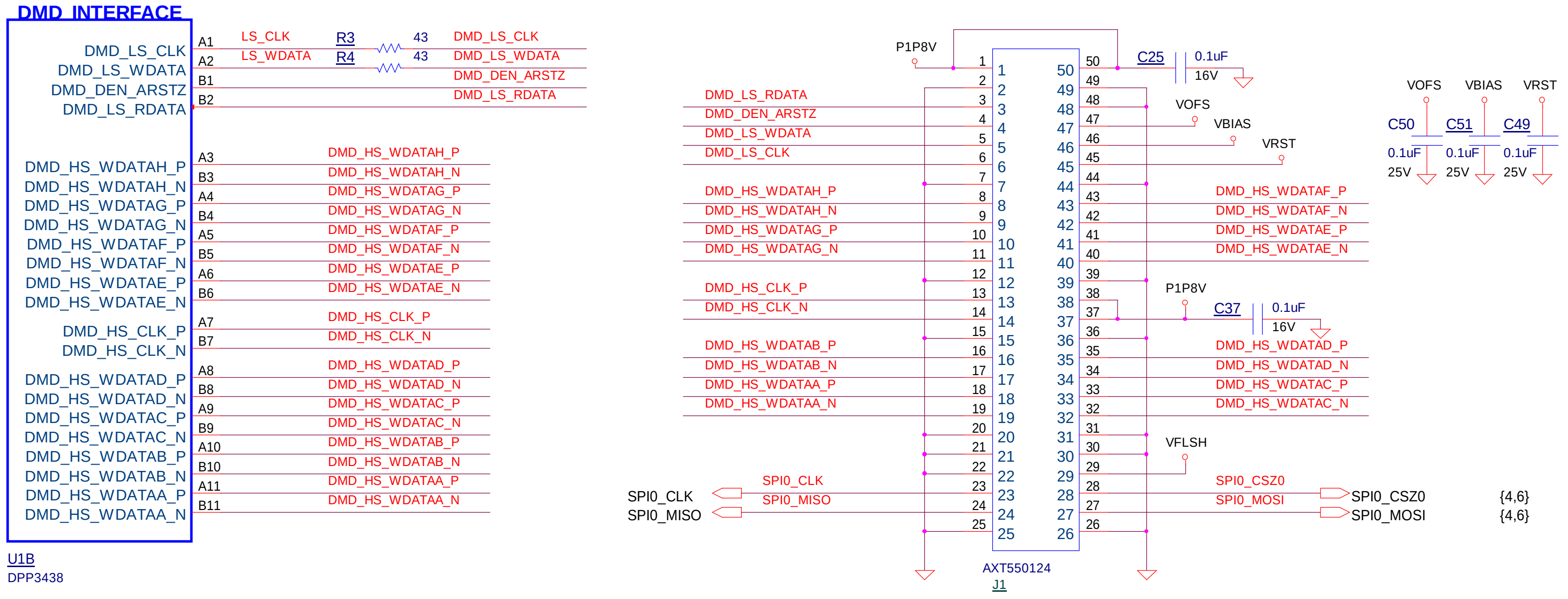
| SYS | Dan Morgan | --- | TITLE Front End Connections |
| APVD | Jeff Dennis | --- | DRAWING NO 2514167 REV B.0 |
| QA | --- | --- | 11 x 17 Orcad Capture 16.2 SHEET 3 of 7 |



DWN Kevin Lowderman DATE JUN-05-2014
ENGR Kevin Lowderman JUN-05-2014
SYS Dan Morgan ---
APVD Jeff Dennis ---
QA --- ---

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TITLE DMD Connection

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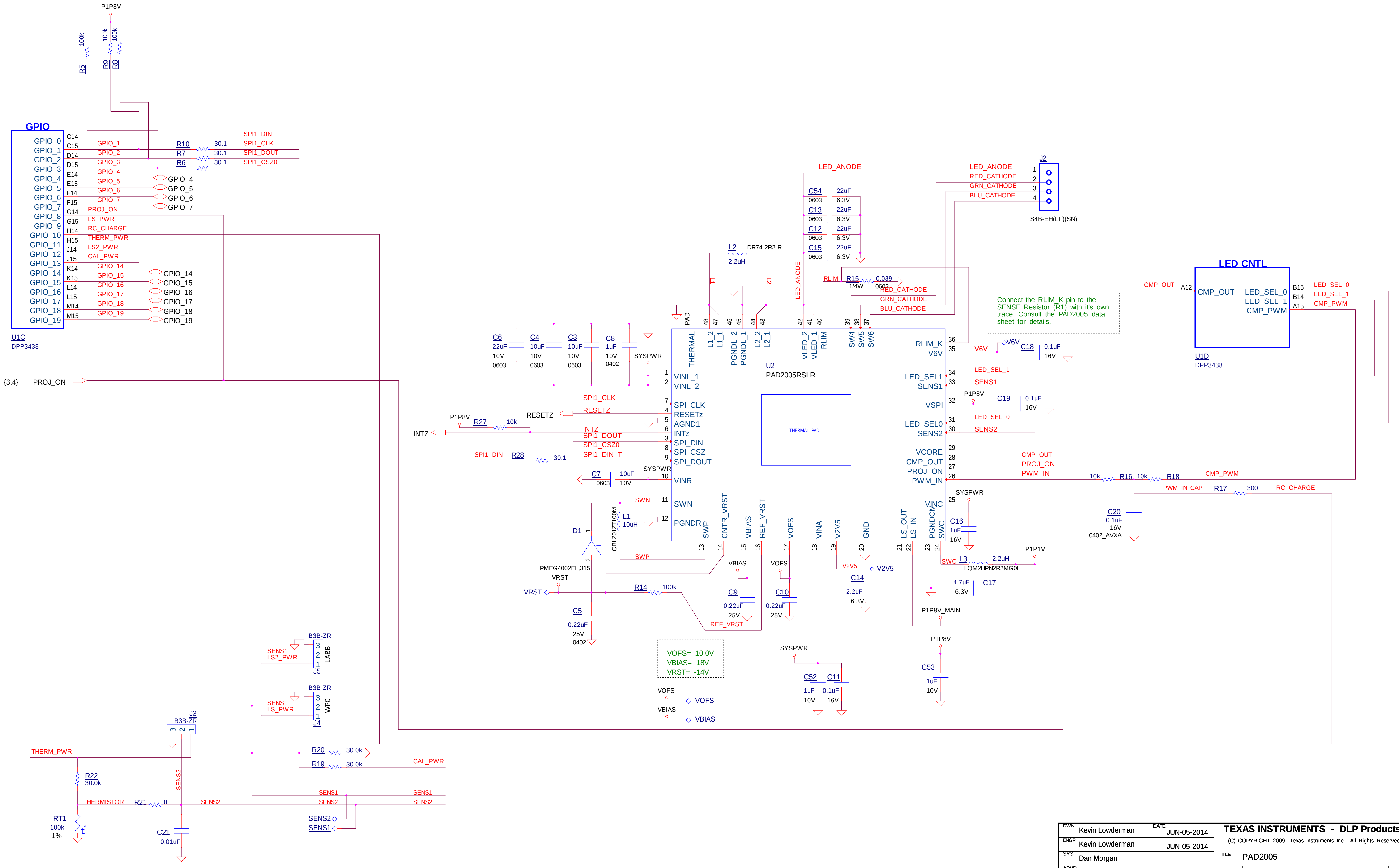

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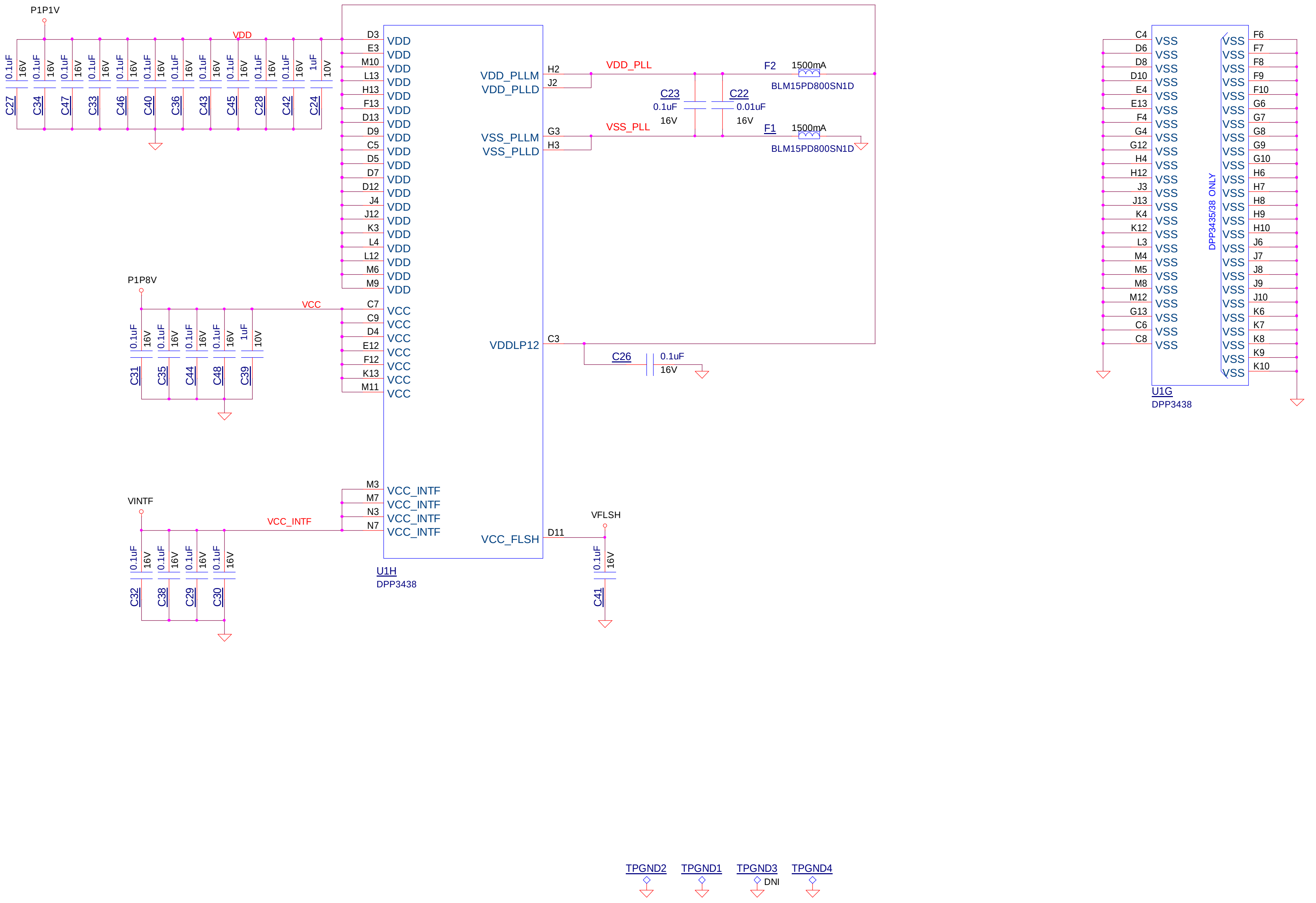
| SYS Dan Morgan | --- | |
| APVD Jeff Dennis | --- | DRAWING NO 2514167 REV B.0 |
| QA --- | --- | 11 x 17 Orcad Capture 16.2 SHEET 5 of 7 |



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| ENGR | Kevin Lowderman | JUN-05-2014 | TITLE DPP3438 Power |
| SYS | Dan Morgan | --- | |
| APVD | Jeff Dennis | --- | DRAWING NO 2514167 REV B.0 |
| QA | --- | --- | 11 x 17 Orcad Capture 16.2 SHEET 6 of 7 |

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